Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	(("5584898") or ("5895583")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 12:33
L2	5778	(polish$3 or abrad$3 or planariz$3) same (silicon adj carbide or "SiC")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 12:36
L3	457	2 same ((silica or silicon adj oxide) same (abrasive or particle))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 12:50
L4	296	3 same diamond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 12:38
L5	166	4 and @pd<"20020802"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 12:41
L6	22	5 and (mix$3 same ratio)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 12:42
L7	711	2 same (bond$3 or join$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 12:51
L8	28	7 and ((diamond same silica) same abrasive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 15:15
L9	28	7 and ((diamond same silica) same (abrasive or particle))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 14:41
L10	3	(wafer same (molecular near bond$3)) same 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 14:45

L11	49	(wafer same (molecular near bond$3)) same (polish$3 or abrad$3 or lapp$3 or planariz$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 14:57
L12	38	11 and (abrasive or particle or grit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 14:47
L13	23	12 and (diamond same silica or silicon adj oxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 14:51
L14	1	12 and (diamond same silica)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 14:52
L15	4192	(wafer same bond$3) same (polish$3 or abrad$3 or lapp$3 or planariz$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 14:58
L16	4	15 same ((diamond same silica) same (abrasive or particle or grit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 14:59
L17	792	((diamond same silica) same abrasive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 15:17
L18	259	17 and ((polish$3 or smooth$3 or planariz$3 or lapp$3 or abrad$3) same wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 15:18
L19	46	17 same ((polish$3 or smooth$3 or planariz$3 or lapp$3 or abrad$3) same wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 15:19
L20	19	19 and ((bond$3 or join$3 or attach$3) same wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 15:40

L21	56	letertre-fabrice.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 15:41
L22	25	letertre-fabrice.in.	US-PGPUB; USPAT	OR	OFF	2005/02/17 15:41
L23	13	(silicon near wafer) same (molecular near bond$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:17
L24	11	23 and (polish$3 or lapp$3 or abrad$3 or smooth$3 or planariz$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:24
L25	531	(grind$3 or polish$3) same ((before or prior) near bond$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:26
L26	0	25 same (silica same abrasive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:26
L27	5	25 and ((silica same abrasive) same diamond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:27
L28	223	slurry same (diamond same silica)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:40
L29	37	28 same (wafer same polish$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:40
L30	75	28 same ((silicon adj carbide) same (polish$3 or grind$3 or lapp$3 or abrading))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:50
L31	44	30 and (wafer same smooth$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:51

L32	44	30 and ((wafer same smooth$3) same polish$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 16:53
L33	41	32 and (bond$3 or join$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 17:02
L34	13	438/455.ccls. and 18	US-PGPUB; USPAT	OR	OFF	2005/02/17 17:03